

Heat Sinks



Overview

As the demands of heat dissipation for electronic devices keep rising, heat sink plays one of the essential components in determining the thermal life and design of many chips or discrete power components in many applications.

ACES offers extrusion/stamping/die-casting for heat sink types with the collaboration of CFM simulation software testing, the clients can select the ACES heat sink to various product solutions such as routers, servers, desktops, edge cards, and other telecom applications with our competitive prices.

Applications



Router



Switch



Gateway



Set Top Box

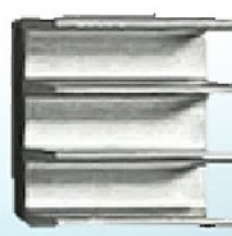


Modem

Extrusion Heat Sink

Heat Sink	Section Dimension (mm)	Surface Treatment
Extrusion	300(L) x 300(W) x 60(H)	Anodize, Chromate

Customized by customer drawing.



Stamping Heat Sink

Heat Sink	Expanded Dimension (mm)	Surface Treatment
Stamping	500(L) x 450(W) x 5(H)	Anodize, Chromate

Customized by customer drawing.



Die-casting Heat Sink

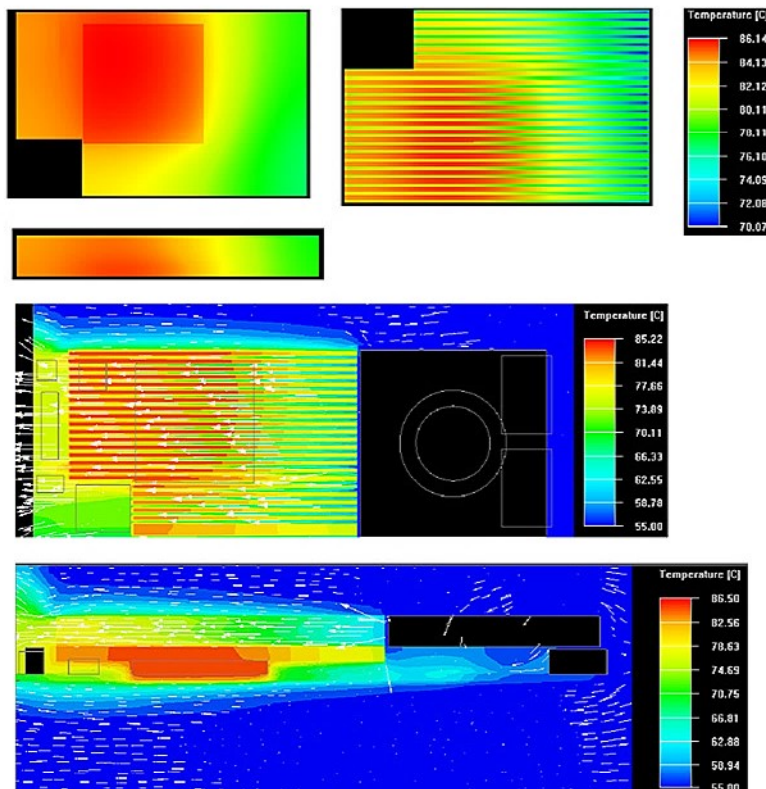
Material	Maximum Dimension (mm)	Surface Treatment
Al	1500(L) x 800(W) x 100(H), T: 0.8	Painting, Powder coating, Anodized...etc.
Mg	1500(L) x 800(W) x 100(H), T: 0.8	
Zn	350(L) x 350(W) x 35(H), T: 0.8	

Customized by customer drawing.



CFM Simulation Software – Testing Case

Cooler type 1
Process: Extrusion
Heat Sink dimension:
54mm x 85mm x 11mm
Fin number: 24
Fin thickness: 0.8mm
Heat Sink base: 3~3.5mm
Fan: 5008 Blower
No CPU block and heat pipe
 $T_c = 85.9^\circ\text{C}$



Testing Equipments



Spectrometer



Salt Spray Tester



HTHU Tester



Hardness Tester



CMM



Universal Tensile